

Features

- ESD Protected Up To 2KV (HBM)
- Trench LV MOSFET Technology
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

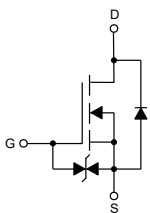
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 190°C/W Junction to Ambient(Notes 2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current	I _D	T _A =25°C	0.75
		T _A =70°C	0.6
Pulsed Drain Current (Note 3)	I _{DM}	3	A
Total Power Dissipation (Note 4)	P _D	0.66	W

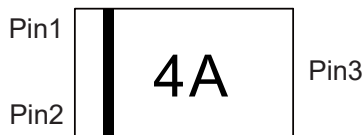
Note:

1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of R_{θJA} is measured with the device mounted on the minimum recommended pad size, in a still air environment with T_A=25°C.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

Internal Structure and Marking Code

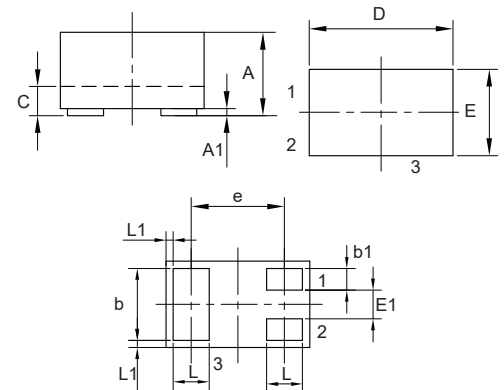


1. GATE
2. SOURCE
3. DRAIN



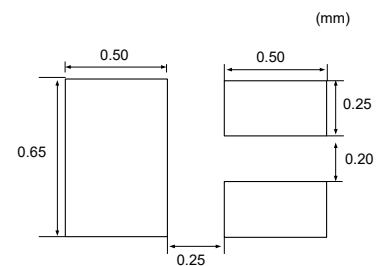
N-Channel MOSFET

DFN1006-3



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.018	0.022	0.45	0.55	
A1	0.000	0.002	0.00	0.05	
b	0.018	0.022	0.45	0.55	
b1	0.004	0.008	0.10	0.20	
c	0.005	0.007	0.12	0.18	
D	0.037	0.042	0.95	1.075	
E	0.022	0.026	0.55	0.675	
E1	0.006	0.010	0.15	0.25	
e	0.026		0.65		TYP.
L	0.008	0.012	0.20	0.30	
L1	0.0002		0.05		TYP.

Suggested Solder Pad Layout



ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	20			V
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.35	0.75	1.1	V
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 10V, V_{DS}=0V$			± 10	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$			1	μA
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=500mA$		190	300	m Ω
		$V_{GS}=2.5V, I_D=400mA$		280	350	
		$V_{GS}=1.8V, I_D=200mA$		440	700	
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_D=750mA$		1.7		S
Gate Resistance	R_g	f=1 MHz, Open drain		37		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				750	mA
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=500mA$			1.2	V
Reverse Recovery Time	t_{rr}	$I_F=500mA, di_F/dt=100A/\mu s$		12		ns
Reverse Recovery Charge	Q_{rr}			0.6		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=16V, V_{GS}=0V, f=1MHz$		27		pF
Output Capacitance	C_{oss}			9.4		
Reverse Transfer Capacitance	C_{rss}			4.6		
Total Gate Charge	Q_g	$V_{DS}=10V, V_{GS}=4.5V, I_D=500mA$		1		nC
Gate-Source Charge	Q_{gs}			0.25		
Gate-Drain Charge	Q_{gd}			0.23		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=10V, V_{GS}=10V, R_G=3\Omega, I_D=500mA$		2		ns
Turn-On Rise Time	t_r			17		
Turn-Off Delay Time	$t_{d(off)}$			14		
Turn-Off Fall Time	t_f			26		

Curve Characteristics

Fig.1 - Typical Output Characteristics

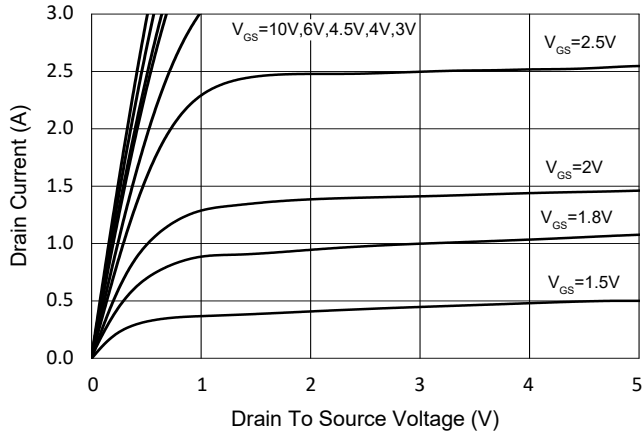


Fig.2 - Transfer Characteristic

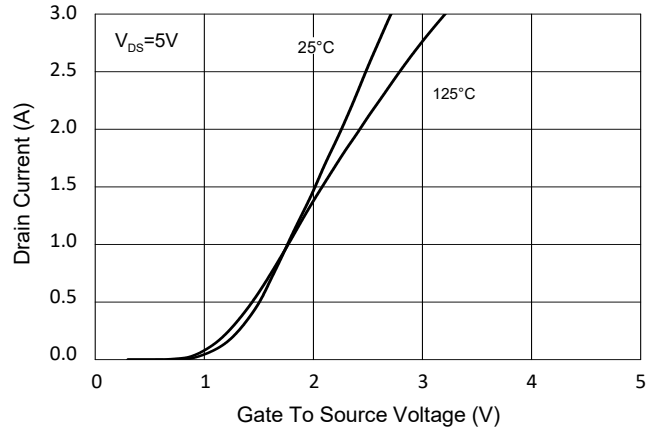


Fig.3 - $R_{DS(ON)}$ - V_{GS}

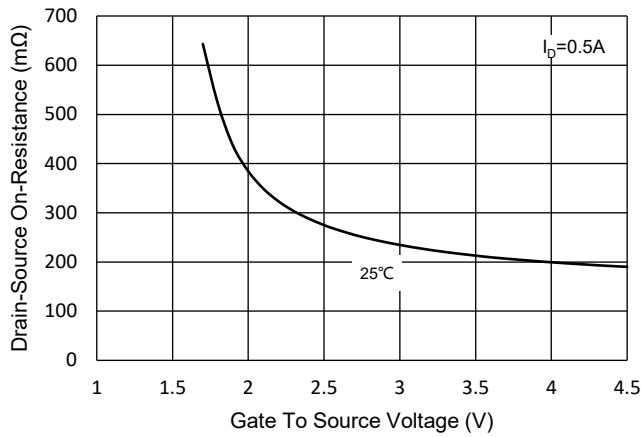


Fig.4 - $R_{DS(ON)}$ - I_D

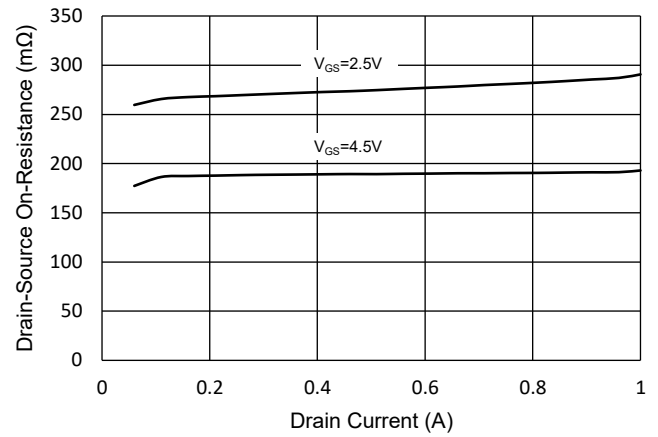


Fig.5 - Capacitance Characteristics

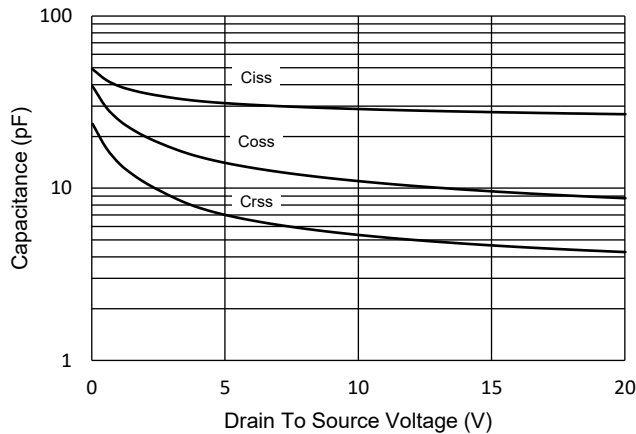
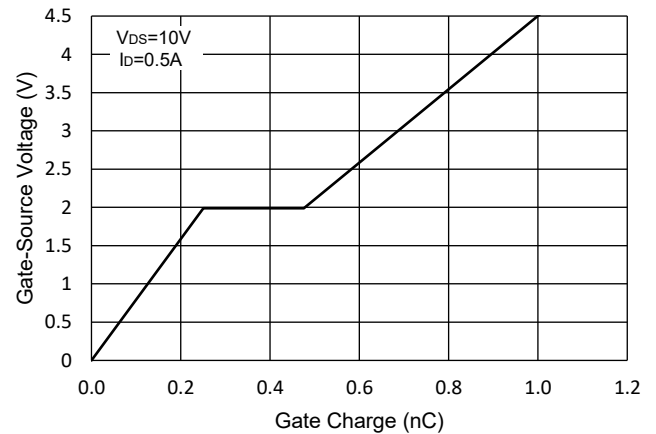


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

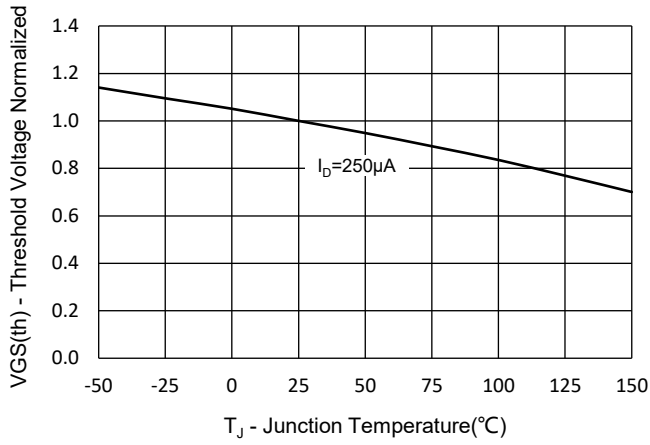


Fig.8 - Normalized On Resistance Characteristics

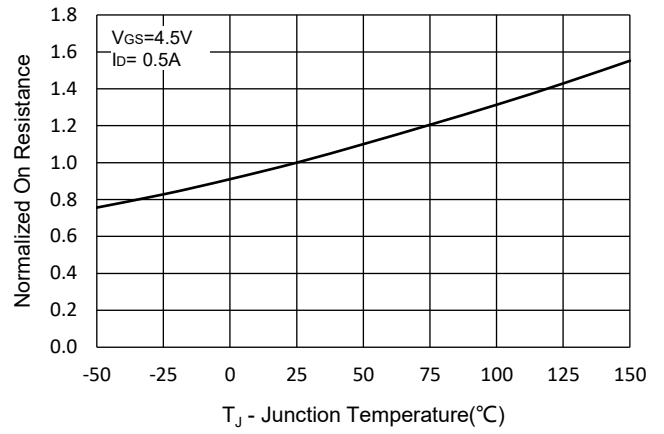


Fig.9 - I_s - V_{SD}

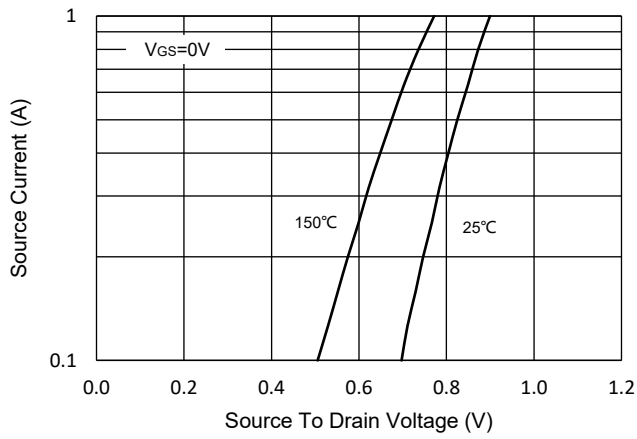


Fig.10 - Drain Current

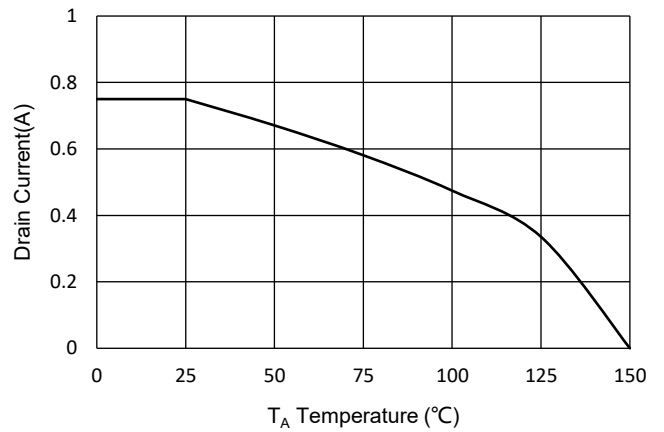
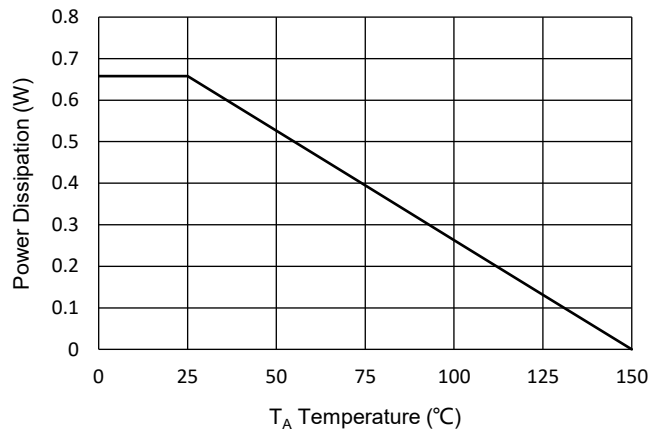


Fig.11 - PD Dissipation



Curve Characteristics

Fig.12 - Safe Operation Area

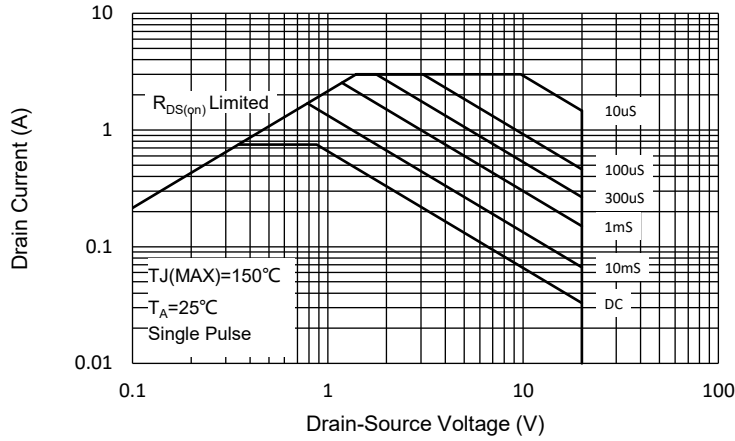
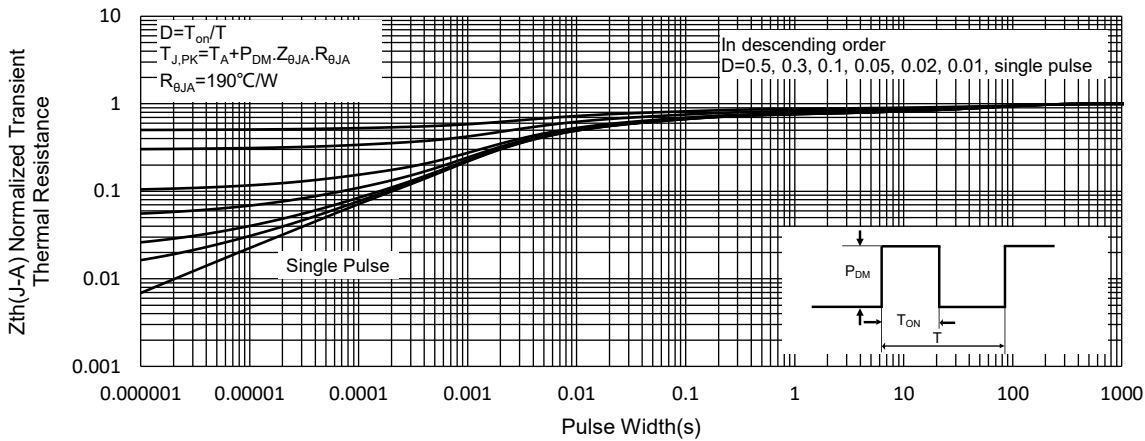


Fig.13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:10Kpcs/Reel

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